



FR30M RFID Dry Inlay Bonder Featuring Tagsurance[®] 3

The FR30M, YTEC's next-generation RFID Dry Inlay Bonder, embodies YTEC's brand's legacy of 30 years in equipment development and integrated system design.

YTEC leverages this expertise to bring innovative solutions to the IoT market.

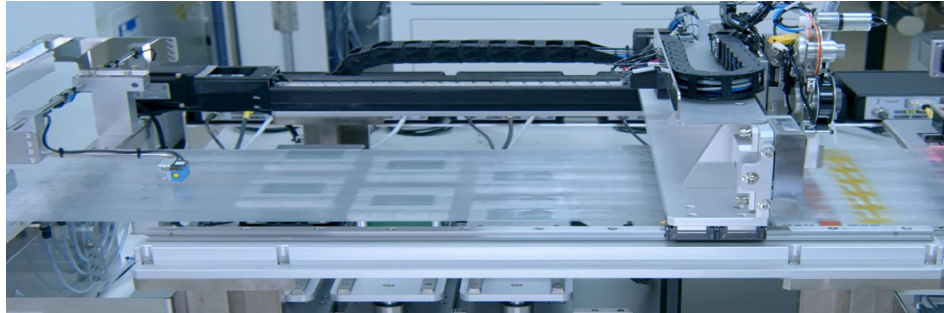
FR30M RFID Dry Inlay Bonder

- UPH of Bonding: 30,000ea/hour
- Bonding Accuracy: $\pm 30\mu\text{m}$
- Bonding Theta (Rotation): $\pm 2^\circ$
- Hot stamping unit: 40 sets
- Temperature: Ambient to $300^\circ\text{C} \pm 5^\circ\text{C}$
- Web width: 40-340mm (Max.)
- Capable of multi-rows for production, testing, slitting and winding



FUNCTIONALITIES

- Web outer diameter software calculation
- Single Jetting valve device and Double Multi-Bonding Arms module
- Real time jetting monitoring and control function
- Jetting monitoring function before bonding
- Real time bonding monitoring
- Hot stamping module programmable control.
- Auto takes tag backside pictures for QC operator visual inspection
- Jetting monitoring after testing



Quality Control with Tagsurance 3

The Tagsurance system gives full visibility into the performance of RFID labels and tags.

- Adjustable test recipe and acceptance criteria
- Multiple tests in a single recipe
- Wide frequency band in use
- RF quality testing
- Reading and verifying memory content
- Quality variance data
- Proof of quality in log files



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